



US005446824A

# United States Patent [19]

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Moslehi

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[54] **LAMP-HEATED CHUCK FOR UNIFORM WAFER PROCESSING**

[75] Inventor: **Mehrdad M. Moslehi, Dallas, Tex.**

[73] Assignee: **Texas Instruments, Dallas, Tex.**

[21] Appl. No.: **63,110**

[22] Filed: **May 17, 1993**

### Related U.S. Application Data

[63] Continuation of Ser. No. 774,677, Oct. 11, 1991, abandoned.

[51] Int. Cl.<sup>6</sup> ..... **H05B 3/00; H01L 21/027; F27D 11/00**

[52] U.S. Cl. .... **392/416; 118/724; 118/50.1**

[58] Field of Search ..... **392/416-418; 219/405, 411, 390; 118/724, 725, 728, 730, 50.1; 250/492.1; 427/55, 50, 51, 585, 586, 592, 557, 569**

### [56] References Cited

#### U.S. PATENT DOCUMENTS

3,836,751	9/1974	Anderson	219/405
4,499,354	2/1985	Hill et al.	118/725
4,599,069	7/1986	Murakami et al.	118/725
4,640,224	2/1987	Bunch et al.	118/725
4,682,566	7/1987	Aitken	118/724
4,709,655	12/1987	Van Mastrigt	118/725
4,796,562	1/1989	Brors et al.	118/725
4,891,335	1/1990	McNeilly	219/530
5,073,698	12/1991	Stultz	219/405
5,119,761	6/1992	Nakata	118/725
5,156,461	10/1992	Moslehi et al.	374/121
5,255,286	10/1993	Moslehi et al.	374/121
5,293,216	3/1994	Moslehi	356/371

#### FOREIGN PATENT DOCUMENTS

60-189924	9/1985	Japan	118/724
60-189927	9/1985	Japan	118/730

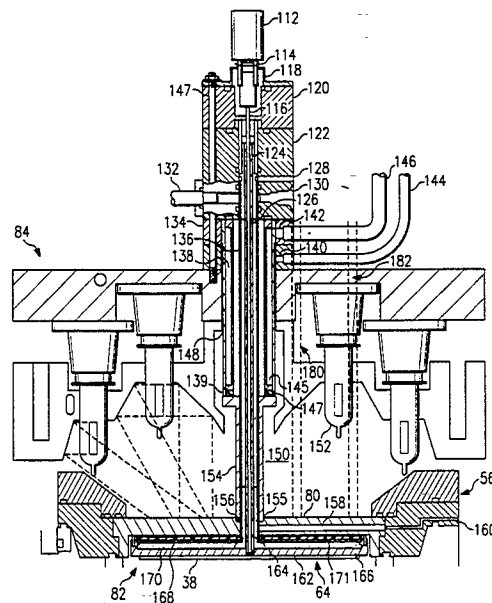
63-58926	3/1988	Japan	.
63-160222	7/1988	Japan	.
64-5014	1/1989	Japan	392/418
3-20464	1/1991	Japan	118/724
3-159224	7/1991	Japan	.
3-256323	11/1991	Japan	.
4-17667	1/1992	Japan	.

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### [57] ABSTRACT

A chuck (82) for lamp-heated thermal and plasma semiconductor wafer (38) processing comprises an absorbing surface (171) for absorbing optical energy from an illuminator module (84) that transforms the electrical energy into radiant optical energy. Chuck (82) includes an absorbing surface (171) that absorbs optical energy and distributes the resultant thermal energy. From the absorbing surface, a contact surface (168) conducts the heat energy to semiconductor wafer (38) and uniformly heats the semiconductor wafer (38) with the distributed thermal energy. Chuck (82) not only provides significantly improved process temperature uniformity, but also allows for the generation of RF plasma for plasma-enhanced fabrication processes as well as for in-situ chamber cleaning and etching. Additionally, chuck (82) provides at least two methods of determining semiconductor wafer temperature; a direct reading thermocouple (112) and association with the pyrometry sensor of illuminator module (84). Other features of chuck (82) are that it is thermally decoupled from the thermal mass of fabrication reactor (50) and establishes an environment for purging optical quartz window (80) surface and semiconductor wafer (38) backside in order to prevent deposition on wafer backside and the quartz window.

**5 Claims, 8 Drawing Sheets**



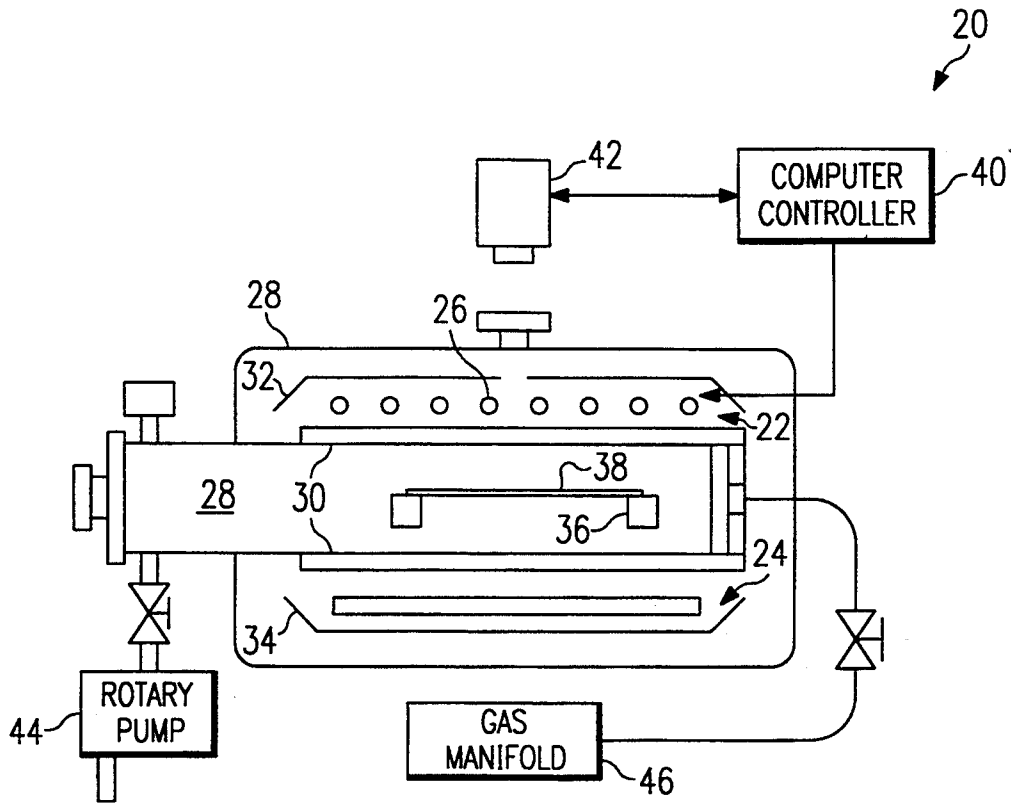


FIG. 1  
(PRIOR ART)

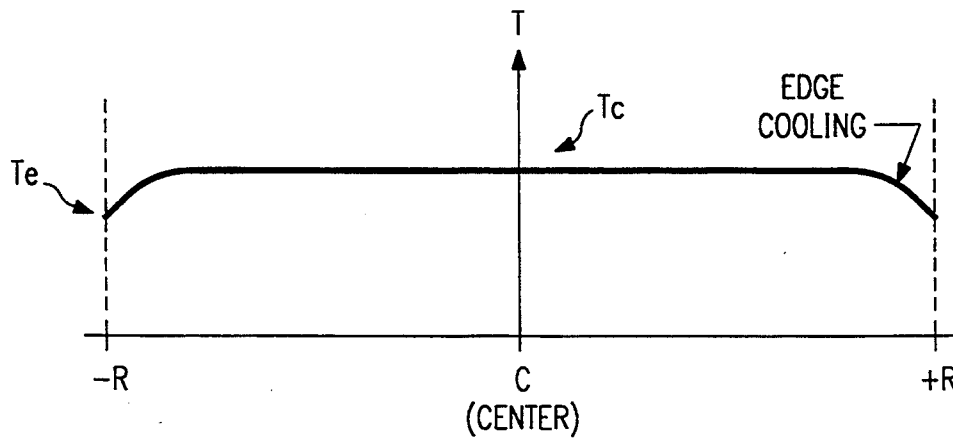


FIG. 2

FIG. 3

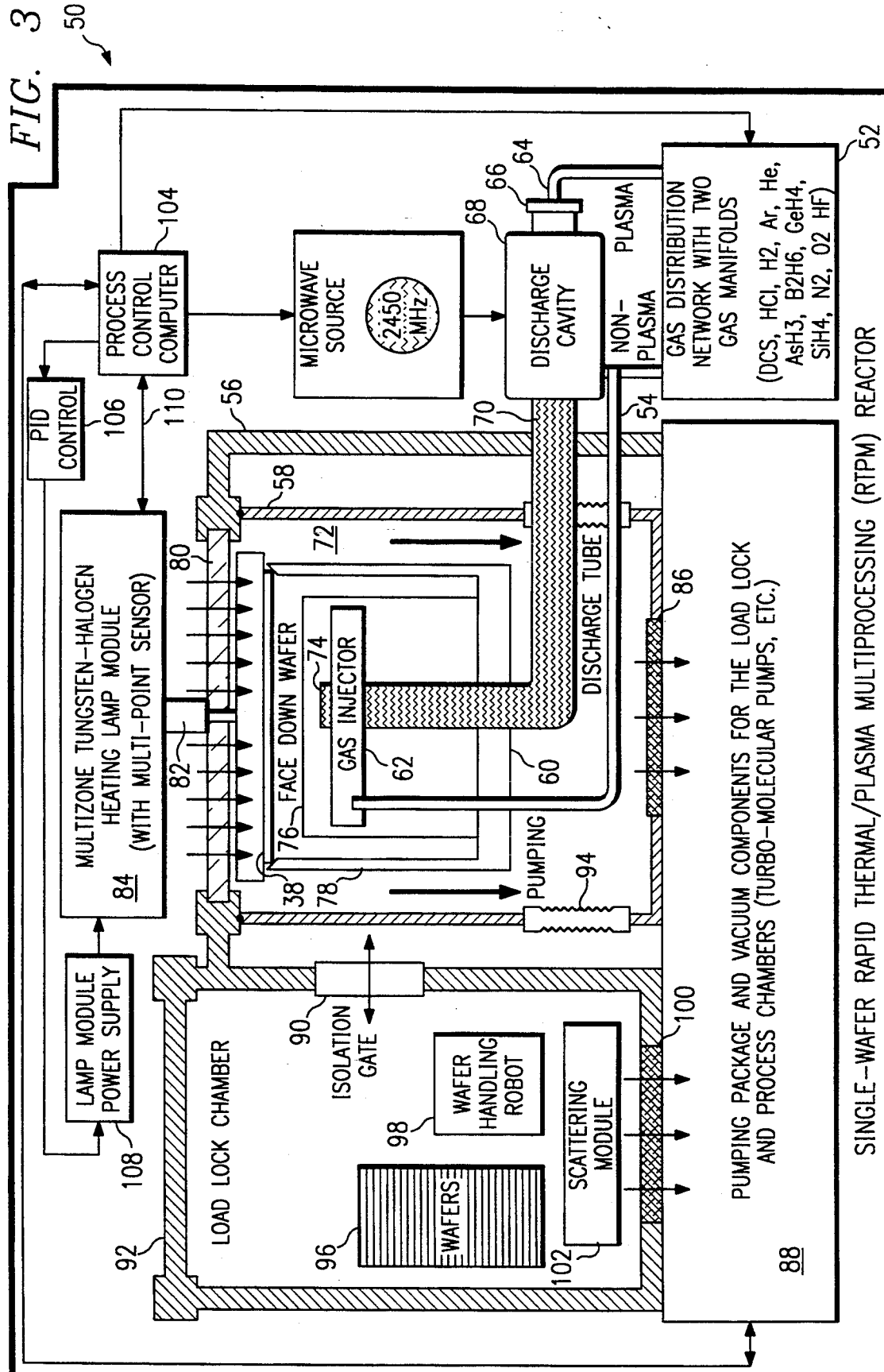


FIG. 3

50

PID CONTROL 106

MULTIZONE TUNGSTEN-HALOGEN HEATING LAMP MODULE 84 (WITH MULTI-POINT SENSOR)

LAMP MODULE POWER SUPPLY 108

LOAD LOCK CHAMBER 92

ISOLATION GATE 90

WAFER HANDLING ROBOT 98

WAFERS 96

SCATTERING MODULE 102

56

58

72

74

76

78

80

82

86

88

94

98

100

102

104

106

110

52

DISCHARGE CAVITY 64

DISCHARGE TUBE 60

GAS DISTRIBUTION NETWORK WITH TWO GAS MANIFOLDS (DCS, HCl, H2, Ar, He, AsH3, B2H6, GeH4, SiH4, N2, O2, HF) 52

PUMPING PACKAGE AND VACUUM COMPONENTS FOR THE LOAD LOCK AND PROCESS CHAMBERS (TURBO-MOLECULAR PUMPS, ETC.) 88

SINGLE-WAFER RAPID THERMAL/PLASMA MULTIPROCESSOR (RTPM) REACTOR 52

62

64

66

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102

104

106

110

52

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DISCHARGE TUBE 60

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NON-PLASMA

PLASMA

GAS DISTRIBUTION NETWORK WITH TWO GAS MANIFOLDS (DCS, HCl, H2, Ar, He, AsH3, B2H6, GeH4, SiH4, N2, O2, HF) 52

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MULTIZONE TUNGSTEN-HALOGEN HEATING LAMP MODULE 84 (WITH MULTI-POINT SENSOR)

PID CONTROL 106

PROCESS CONTROL COMPUTER 104

MICROWAVE SOURCE 2450 MHz

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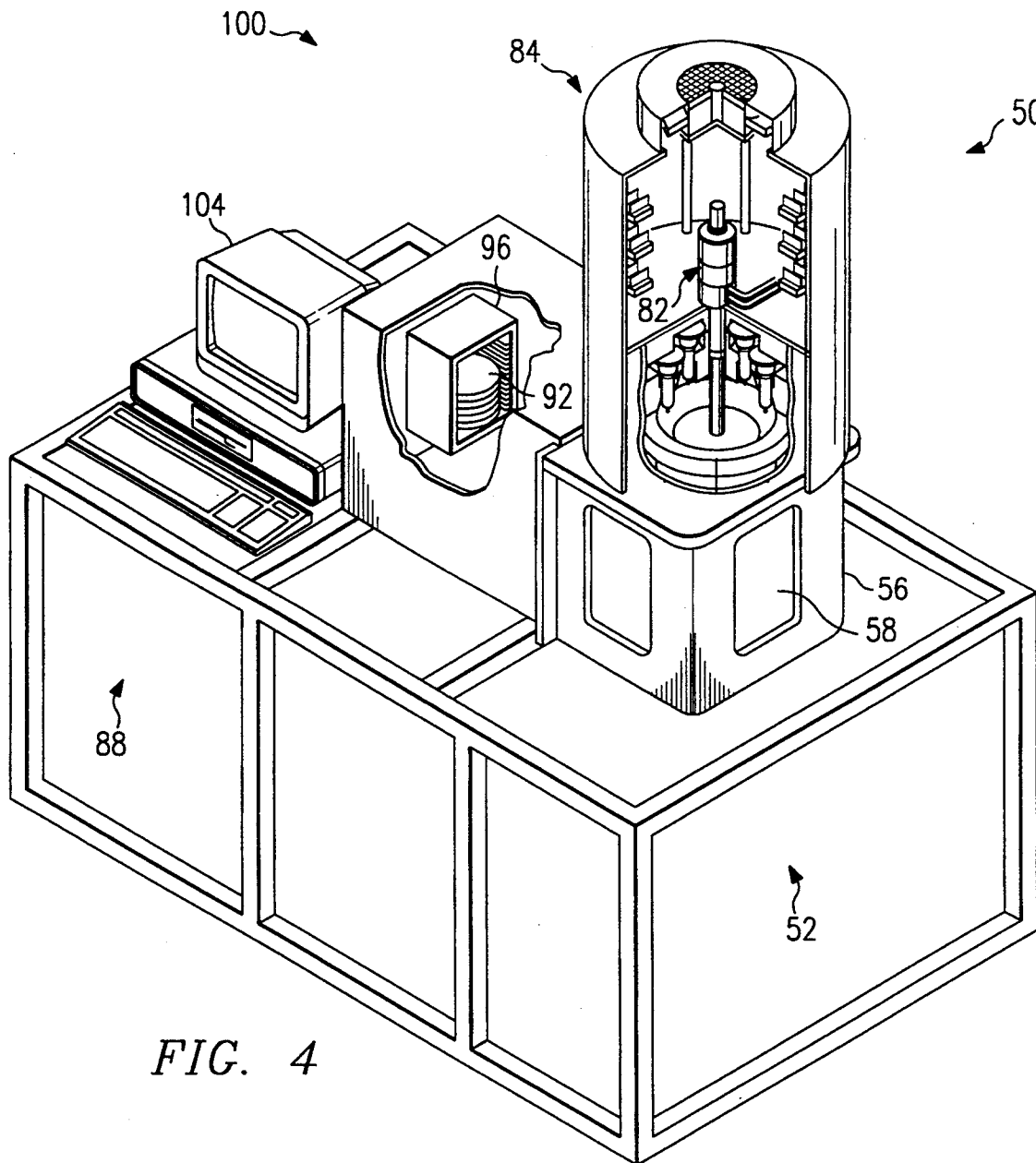


FIG. 4

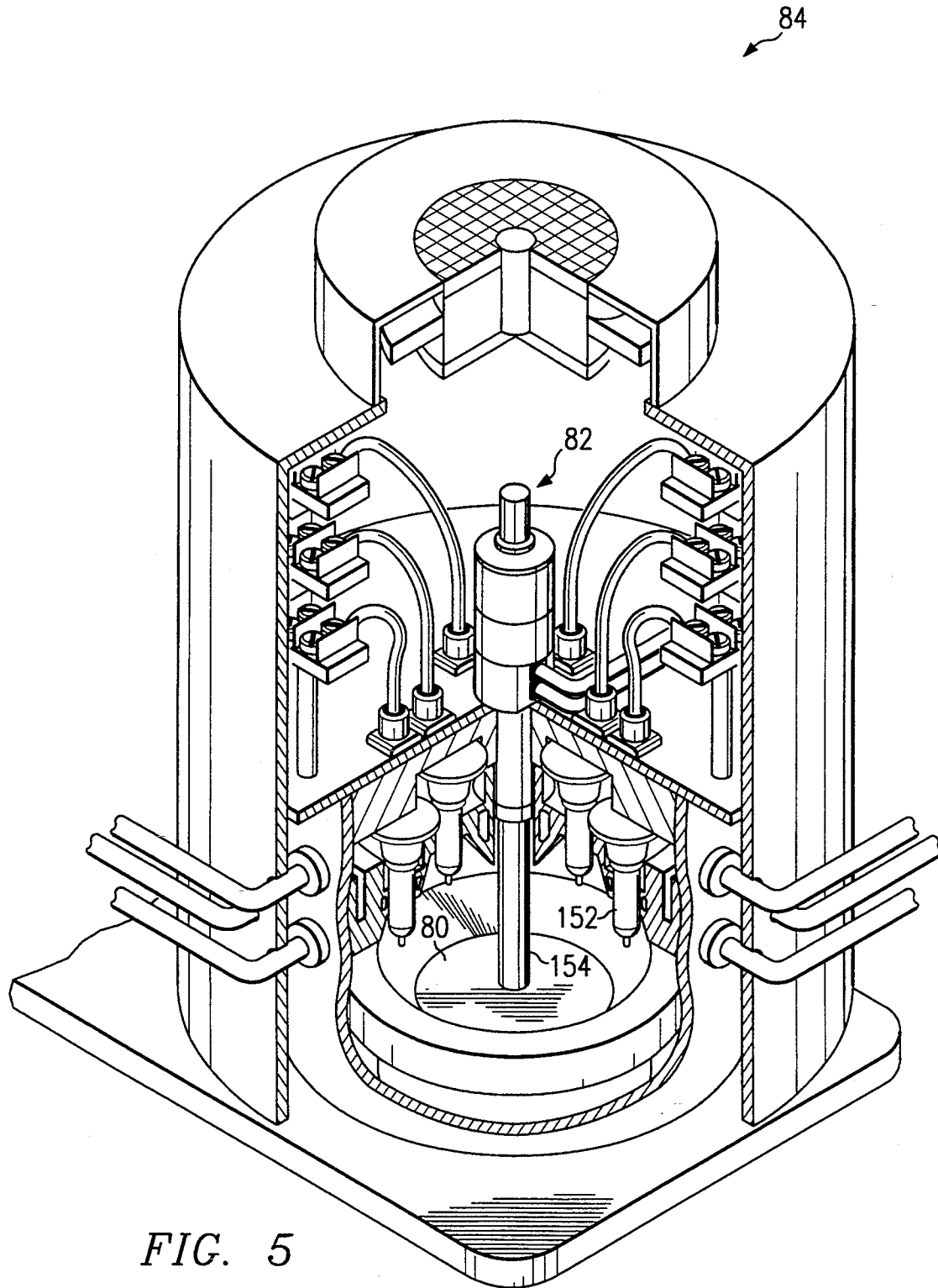


FIG. 5

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